ASSOCIATION CONNECTING	© Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	Il rights reserved untions.	under both	This docume evel parts, ti	ent is a declaration	ion of the sencompasse	substances es all lowe	within the manufactu r level materials for v	rer listed i which the r	tem. Note: it nanufacturer	f the item is an as has engineering	ssembly with lower responsibility.	
1752-21.1				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and M	als and Mfg Information					
Supplier Inform	ation														
Company name*			Company unique ID			1	Unique ID Authority				Respon	Response Date*			
onsemi											2025-05	2025-05-09			
Contact Name			Title - Contact]	Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative]	Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com			
Requeste	uester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	e Version	Version Manufacturing Site			Weight*	UOM	Unit Type	
		NCID920	ICID9200R2 High Speed Dual C T&R		Channel Digital I	Isolator	2025-05-09	05-09 PBB			423.399	mg	Each		
Manufacturing l	Proccess Information	1													
Terminal Plating / Grid Array Material T			Ferminal Base Alloy J-STD-020 MS		J-STD-020 MSL	Rating	Peak Pro	Peak Process Body Temperature Max Time		re Max Time at Peal	ak Temperature Number of Reflow Cycles		cles		
Matte Tin (Sn) - annealed CU			J Alloy 1			260 C 30			seconds 3						
Comments															
level 1 - maximum ti	me at peak temperature o	luring sol	dering is 10-3	0 seconds											
For more informatio	on regarding material con	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
DBC	54.376	mg	Supplier	Silver (Ag)	7440-22-4		0.0816	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		38.7918	mg
			В	Nickel (Ni)	7440-02-0		0.1305	mg
			Supplier	Copper (Cu)	7440-50-8		15.3721	mg
Die	2.997	mg	Supplier	Silicon (Si)	7440-21-3		2.997	mg
Epoxy	0.036	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0032	mg
			Supplier	Proprietary	Proprietary Data		0.0002	mg
			Supplier	Bismaleimide	13676-54-5		0.0182	mg
			Supplier	PTFE	9002-84-0		0.0144	mg
Lead Frame	65.486	mg	Supplier	Silver (Ag)	7440-22-4		0.1965	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1244	mg
			Supplier	Iron (Fe)	7439-89-6		1.6961	mg
			Supplier	Copper (Cu)	7440-50-8		63.3773	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0917	mg
Mold Compound-Black	296.395	mg		Epoxy resin	proprietary data		17.7837	mg
			Supplier	Phenolic Resin	Proprietary Data		17.7837	mg
			Supplier	Carbon Black (C)	1333-86-4		1.482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		251.9357	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		7.4099	mg
lating	3.143	mg	Supplier	Tin (Sn)	7440-31-5		3.143	mg
Solder Paste	0.595	mg	Supplier	Silver (Ag)	7440-22-4		0.0149	mg
			А	Lead (Pb)	7439-92-1	7a	0.5504	mg
			Supplier	Tin (Sn)	7440-31-5		0.0298	mg
Wire Bond - Au	0.371	mg	Supplier	Gold (Au)	7440-57-5		0.371	mg